



Material Content Data Sheet



Sales Product Name		BSC019N04NS G		Issued		25. January 2018		
MA#		MA001637814						
Package		PG-TDSON-8-39		Weight*		114.01 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.071	3.57	3.57	35709	35709
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		128	
	non noble metal	iron	7439-89-6	0.049	0.04		427	
	non noble metal	copper	7440-50-8	48.649	42.68	42.73	426710	427265
	non noble metal	copper	7440-50-8	0.031	0.03	0.03	272	272
wire	non noble metal	copper	7440-50-8	0.031	0.03	0.03	272	272
encapsulation	organic material	carbon black	1333-86-4	0.078	0.07		687	
	plastics	epoxy resin	-	6.186	5.43		54258	
	inorganic material	silicondioxide	60676-86-0	32.887	28.85	34.35	288460	343405
leadfinish	non noble metal	tin	7440-31-5	1.520	1.33	1.33	13332	13332
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1390	1390
solder	non noble metal	tin	7440-31-5	0.066	0.06		576	
	noble metal	silver	7440-22-4	0.082	0.07		720	
	non noble metal	lead	7439-92-1	3.135	2.75	2.88	27500	28796
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
	non noble metal	iron	7439-89-6	0.017	0.01		149	
	noble metal	silver	7440-22-4	0.150	0.13		1316	
	non noble metal	copper	7440-50-8	16.910	14.83	14.97	148321	149831
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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